

注意事项 Note

— 支架成型 LeadForming 1、引线成型需在焊接前完成。Leadshapingneedstobedonebeforewelding. 2、不能以靠近环氧体的支架根部为支点成型。Cannotbeformedatthebaseofthesupportneartheepoxy. 3、成型位置应离环氧本体 5mm 以上，特殊情况需在 5mm 以下，（但应 $\geq 2\text{mm}$ ）成型的，应制作特制的夹具，成型时固定住靠近环氧体的管脚部位，尽管减少对环氧体的作用应力，防止因应力过大造成产品开路及其环氧体裂损。Formingpositionsshouldbeabove5mmfromepoxybody, specialcaseshould bebelow5mm(but $\geq 2\text{mm}$)molded, A special fixture shall be made to hold the pin close to the epoxy during molding, although reducing the stress on the epoxy, Prevent product opening and epoxy cracking due to excessive stress

— 储存 Storage 1、该产品出厂后贮存的条件应为 $0\sim +30^{\circ}\text{C}$ 、相对湿度不大于 70%，贮存期限为 3 个月。若贮存超过 3 个月，则应放在带有氮气和干燥剂的密闭容器内，贮存时间可达一年。The storage conditions of the product after leaving the factory shall be $0\sim 30^{\circ}\text{C}$, the relative humidity shall not be greater than 70%, and the storage period shall be 3 months. If stored for more than 3 months, it should be placed in a sealed container with nitrogen and desiccant for up to one year. 2、拆袋使用，应尽可能短时间内用完，若用不完，应满足贮存条件应为 $0\sim +30^{\circ}\text{C}$ 。相对湿度不大于 60%，并在 2 天内安装完。产品支架是铁合金表面上镀银，银表面会受到腐蚀性气体等环境的影响，应避免使产品处于易腐蚀或失去光泽的环境中，这会导致产品焊接困难。Use of bag removal, should be used as short as possible, if not used, should meet the storage conditions should be $0\sim 30^{\circ}\text{C}$. The relative humidity is not more than 60% and is installed in 2 days. The product support is silver plated on the surface of ferroalloy, the silver surface will be affected by corrosive gas and other environment, should avoid making the product in the environment of easy corrosion or loss of luster, which will lead to difficult welding of the product.

— 安装 Installation 1、产品安装在 PCB 上，不能造成对引线施加压力。A product installed on a PCB cannot cause pressure on the lead. 2、建议 LED 使用时，需串电阻作业，以防止大电流或大电压烧损芯片，有部分客户投诉亮度不均及色泽不均，均为大电流或大电压烧损所致。A series of resistance operations are recommended LED use to prevent high current or high voltage from burning the chip. Some customers complain that the brightness is uneven and the color is uneven. 3、LED 在剪脚时建议采用自动机台进行剪脚，且保持刀片锋利，以防止扭距应力拉扯胶体与支架，产生应力破坏 LED 内部结构。LED it is recommended to use automatic machine to cut the feet, and keep the blade peak profit, so as to prevent torsion stress pulling colloid and support, resulting in stress damage LED internal structure. 4、建议 LED 成形加工时在焊锡前，如在焊锡后立即进行加工，此时 LED 胶体内部还存在一定的温度，若用手碰触或外力碰触到胶体，因胶体特性会产生应力拉扯断第二焊点。

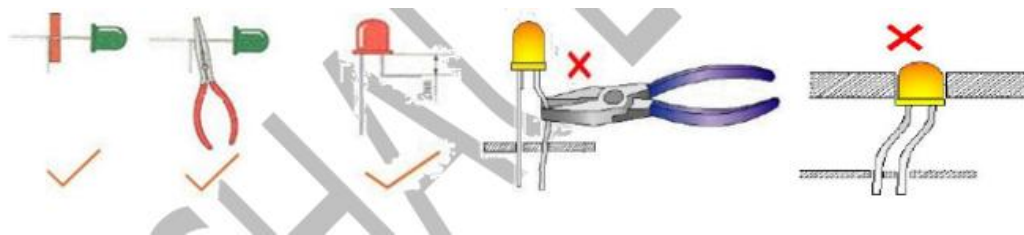
LED is suggested that there is a certain temperature inside the colloid when it is processed before the solder, if it is processed immediately after the solder, if the colloid is touched by hand or by external force, the second spot will be broken due to the colloidal characteristics.

5、支架成形形状需要与 PCB 上的间距一致，以防止 LED 在插在 PCB 上有拉扯的状况。The shape of the bracket needs to be aligned with the spacing on the PCB to prevent LED from pulling on the insert.

6、LED 在折脚加工时，建议固定 LED PIN 脚后进行加工，以防止应力的产生。LED in folding foot processing, it is recommended to fix LED PIN foot after processing to prevent stress generation.

7、需离胶体 2 毫米才能折弯支架。2mm from colloid to bend support.

8、折脚方式如下 The foot folding method is as follows:



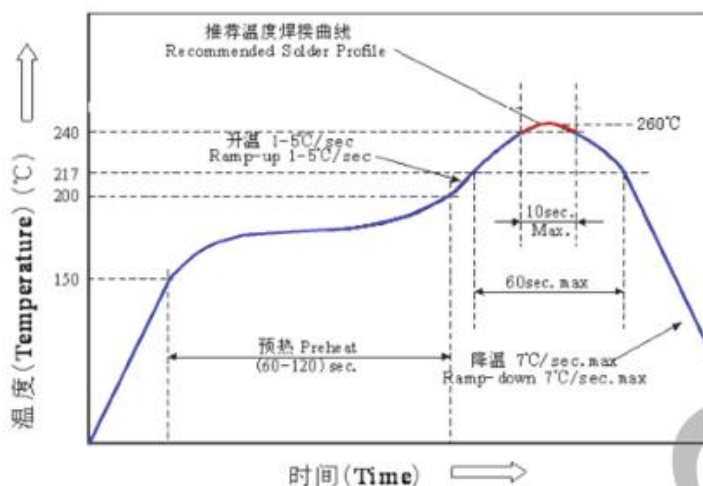
—焊接 Soldering

1、胶体不可侵入锡槽内。Epoxy non-invasive in tank.

2、加热过程中不能对引脚施加压力。Pin pressure cannot be applied during heating.

3、推荐焊接条件 $260^{\circ}\text{C} < 3\text{s}$ Recommended welding conditions $260^{\circ}\text{C} < 5\text{s}$ or 340°C
Customers are advised to install fan after wave peak welding to facilitate heat dissipation, need to wait for LED cooling (preferably after room temperature) before the next process processing.

推荐波峰焊曲线 The wave peak welding curve is recommended:



—清洗 Cleaning 1、在任何情况下，清洗时间应在常温 1 分钟之内进行。In any case, the cleaning time should be within 1 minute of normal temperature. 2、清洗产品时推荐使用酒精作为清洗剂，如使用其他清洗剂，需先确认清洗剂是否会腐蚀环氧体。氟利昂不能作为清洗剂。

It is recommended to use alcohol as a cleaning agent when cleaning products. If other cleaning agents are used, it is necessary to confirm whether the cleaning agent will corrode the epoxy body first. Freon can't be a cleaning agent. 3、不可用水清洗，以免腐蚀引线，建议使用酒精。Donot wash with water to avoid corrosion of leads, alcohol is recommended 4、用超声波清洗产品时，超声波功率和时间分别小于 300W 和 30 秒；PCB 和产品不能接触振荡器，不能使 PCB 上的产品产生共振。Whencleaning the product with ultrasonic, the ultrasonic power and time are less than 300 W and 30 seconds, respectively; PCB and products can not contact the oscillator, can not make the product on the PCB resonance. 5、本型号为静电敏感器件，所以静电和电泳会损坏产品，要求使用时佩戴防静电手环，所有的装置、设备、机器、桌子、地面都必须防静电接地。This model is an electrostatic sensitive device, so electrostatic and electrophoretic will damage the product, it is required to wear anti-static bracelet when all devices, equipment, machines, tables, ground must be anti-static grounding. --其他 Other 1、以上规格可更改，恕不另行通知。洲光源将为上述规格的材料变更保留权力 Above specification maybe changed without notice. CHAU LIGHT will reserve authority on material change for above specification. 2、当使用此产品时，请观察这些规格表中概述的绝对最大额定值和使用说明。洲光源不承担任何损坏结果的责任从不符合绝对最大额定值的产品的使用和这些规格表中包含的说明 When using this product, please observe the absolute maximum ratings and the instruction for using outlined in these specification sheets. CHAU LIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets. 3、此规格书版权属广东洲光源红外半导体有限公司。未经允许不得转载或复印。These specification sheets include materials protected under copyright of CHAU LIGHT corporation. Please don't reproduce or cause anyone to reproduce them without CHAU LIGHT's consent. 地址(Add): 中山市东升镇联胜南路3号 电话(Tel): 0760-88504720 传真(Fax): 0760-88504721 网站(Web): www.zgy-led.com